IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: BAYAN et al.

Attorney Docket No.: NSC1P295/P05886

Application No.: 10/789,258

Examiner: DOAN, Theresa T.

Filed: February 26, 2004

Group: 2814

Title: DIE ATTACH PAD FOR USE IN

SEMICONDUCTOR MANUFACTURING AND

METHOD OF MAKING SAME

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Confirmation No.: 9477

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I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 22, 2007.

Signed:

Sue Funchess

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AMENDMENT D

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Dear Sir:

In response to the Final Office Action dated February 8, 2007, please amend the above-identified patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.